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## PATENT ABSTRACTS OF JAPAN

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ASANO YUICHI**(54) **LEAD FRAME**(57) **Abstract**

**PURPOSE:** To rigidly solder leads to the pattern of a printed circuit board by reducing in thickness the cut part of the lead to provide a step, and covering the cut face of the end of the lead with a solder-plating layer.

**CONSTITUTION:** When a lead 2 of a lead frame 1 is cut from the opposite face side of the lead 2 to a step formed face, a solderplating layer 1a formed on the surface of the opposite face is elongated to the cut face by shearing at the time of cutting to cover the cut face of the lead 2. Thus, when the lead 2 formed with the solder-plating layer 1a is brought into contact with the pattern 7a of the printed circuit board 7 to be soldered to the cut face of the lead 2, the solder-plating layer 1a is provided on the cut face of the end of the lead 2. Thus, the solder is adhered to the cut face of the end to be rigidly soldered, and an apparent soldering can be confirmed even in a user's inspection.

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